

### Features

- 5050 with integrated high quality constant current IC and RGB LED chip.
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meters
- Data transfer rate of 800 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp.
- SA-I Anti-interference patent technology for single line data transmission.
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

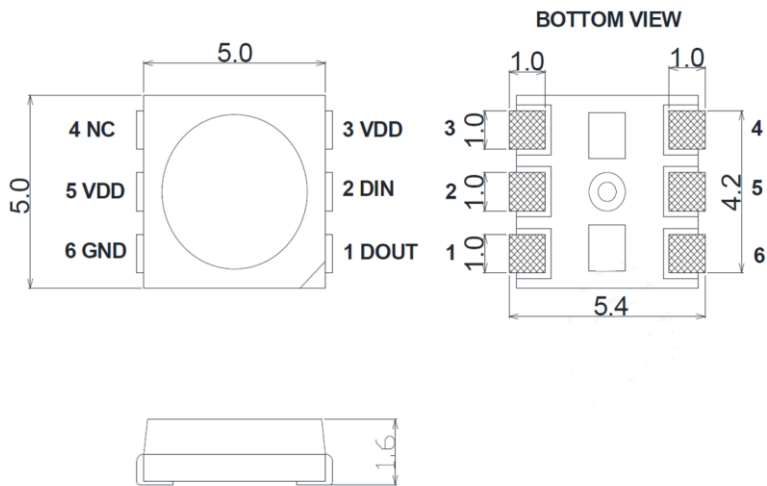
### Description

The IN-PI55TBTPRGPB is 5.0\*5.0\*1.6mm RGB LED with integrated IC. It is a SMD type LED which can be used in various applications.

### Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

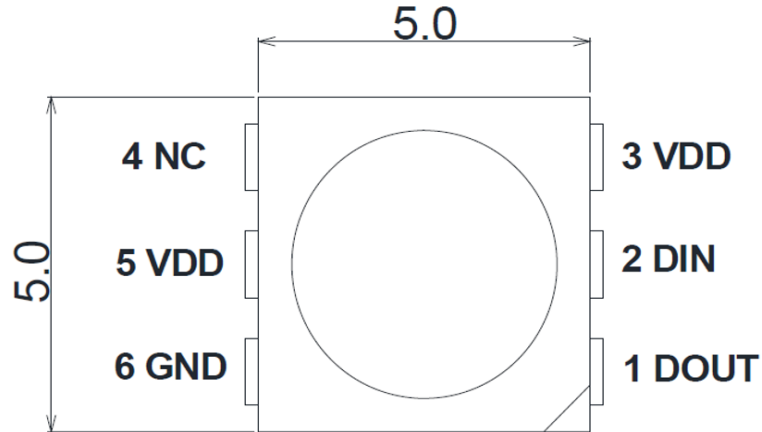
### Package Outline Dimensions & Pin Configuration



- Notes:
1. All dimensions are in millimeters.
  2. Tolerance is  $\pm 0.1$ mm unless otherwise noted

**Figure 1. IN-PI55TBTPRGPB Package Outline Dimensions**

### Pin Configuration



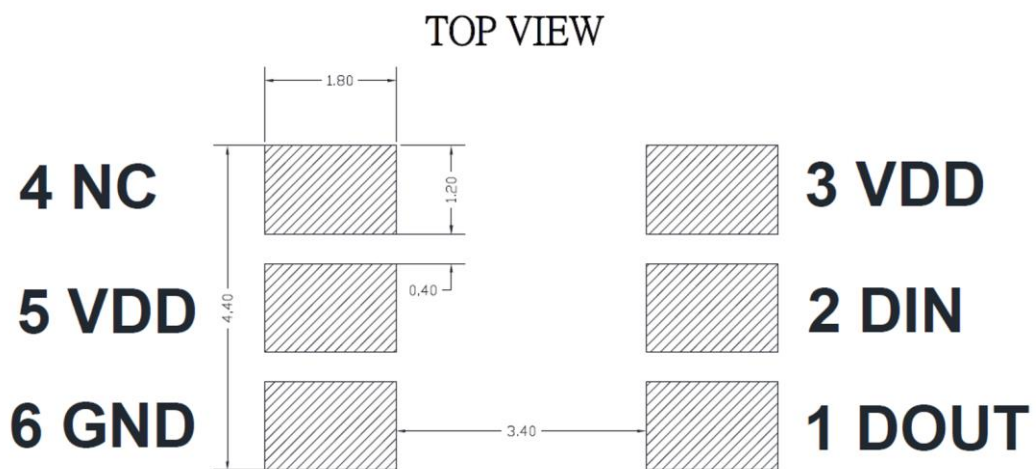
**Figure 2. IN-PI55TBTPRGPB Pin Configuration**

**Notes:**

1. Dimension in millimeter, tolerance is  $\pm 0.1\text{mm}$  unless otherwise noted.

Number	Symbol	Function Description
1	DOUT	Control data signal output
2	DIN	Control data signal input
3	VDD	Power Supply LED
4	NC	NC
5	VDD	Power supply LED
6	GND	Ground

### Soldering Pad Size



**Absolute Maximum Rating** ( $T_a = 25\text{ }^\circ\text{C}$ ,  $V_{SS}=0\text{V}$ )

Parameter	Symbol	Range	Unit
Logic supply voltage	$V_{DD}$	+3.7~+5.5	V
Logic input voltage	$V_{IN}$	-0.5 ~VDD+0.5	V
Operating temperature	$T_{OPT}$	-45 ~ +85	$^\circ\text{C}$
Storage temperature	$T_{STG}$	-45 ~ +85	$^\circ\text{C}$
ESD pressure(HBM)	$V_{ESD}$	2K	V
ESD pressure(DM)	$V_{ESD}$	200	V

**LED Characteristics** ( $T_a = 25^\circ\text{C}$ )

 $(T_a = -25^\circ\text{C}$ , unless otherwise specified)

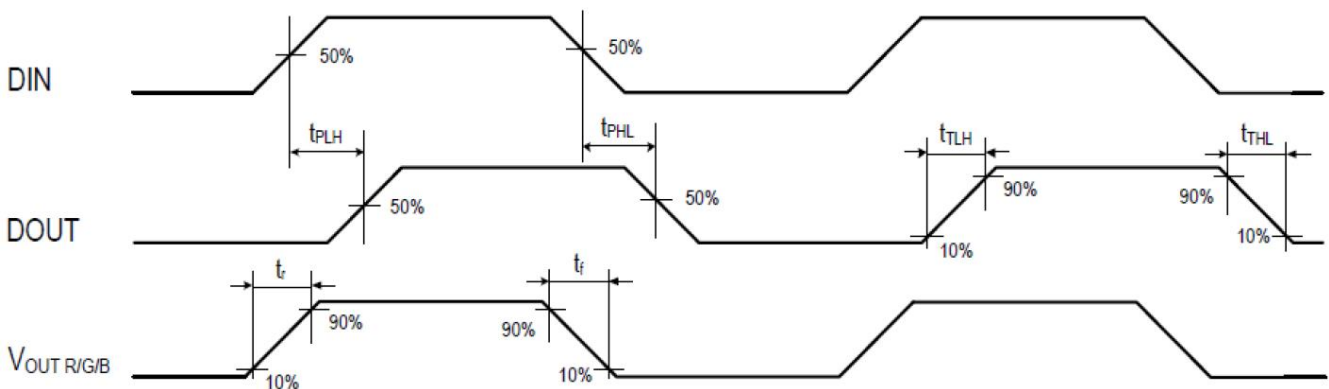
Light color	Wavelength (nm)	Light intensity (mcd)	Working current (mA)	Working voltage (V)
R	620-625	400-700	12	1.8-2.2
G	520-525	1000-1500	12	2.8-3.2
B	465-470	200-400	12	2.8-3.2

**Recommended Operating Ranges** (unless otherwise specified,  $T_A=25\text{ }^\circ\text{C}$ ,  $V_{DD}=4.5\text{ ~ }5.5\text{V}$ ,  $V_{SS}=0\text{V}$ )

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
Supply voltage	$V_{DD}$	-	5.2	-	V	-
High level input voltage	$V_{IH}$	0.7*VDD	-		V	VDD=5.0V
Low level input voltage	$V_{IL}$	-	-	0.3*VDD	V	VDD=5.0V
The frequency of PWM	$F_{PWM}$	-	1.0	-	KHZ	-
Static power consumption	$I_{DD}$	-	0.5	-	mA	-

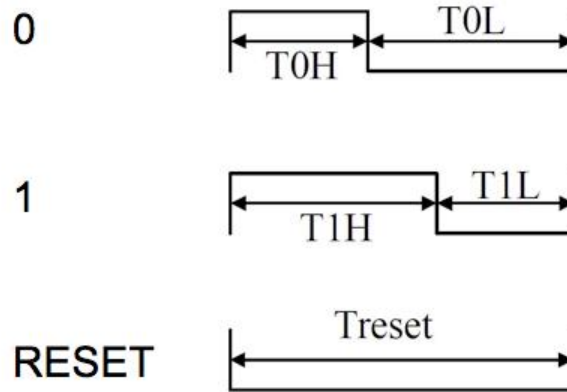
**Switching Characteristics** (unless otherwise specified,  $T_A=25\text{ }^\circ\text{C}$ )

Parameter	Symbol	Min	Typical	Max	Unit	Test conditions
The speed of data transmission	fDIN	---	800	---	KHZ	The duty ratio of 67% (data 1)
DOUT transmission delay	TPLH	---	67	---	ns	The earth load capacitance of the dout port is 30pf, and the signal transmission delay from DIN to dout
	TPHL	---	82	---	ns	
Out R/B conversion time	Tr	---	22	---	ns	IOU <sub>T</sub> R / B= 5mA, out R / B port connected with 200 $\Omega$ resistor to VDD in series, load capacitance to ground
	Tf	---	75	---	ns	
Out G conversion time	Tr	---	18	---	ns	IOU <sub>T</sub> g = 5mA, out g port is connected with 200 $\Omega$ resistor to VDD in series, and the load capacitance to ground is 30pf
	Tf	---	110	---	ns	



## Timing Waveforms

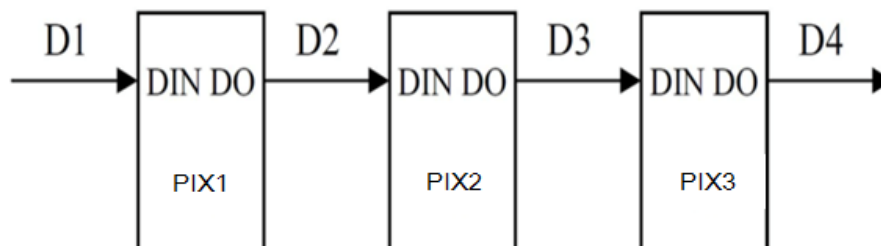
### 1. Input Code



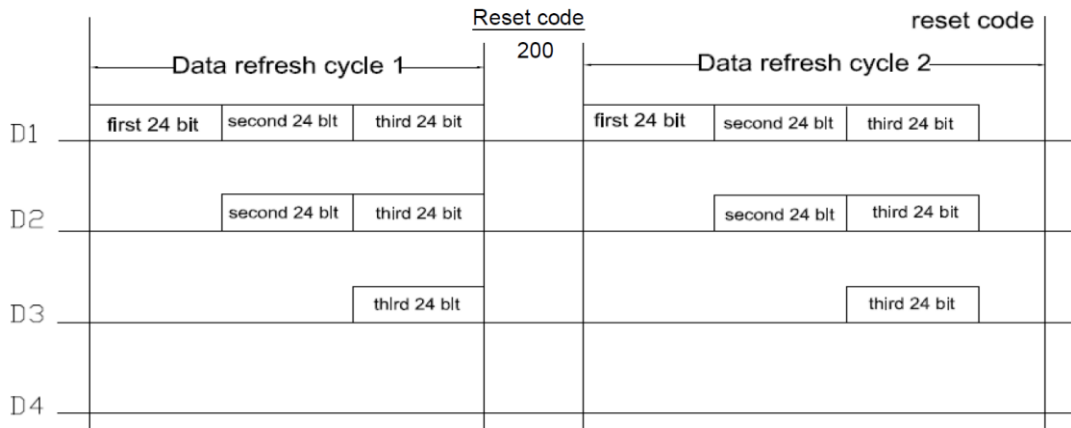
### 2. The data transmission time ( $T_H+T_L=1.25\mu s\pm 600ns$ ):

Name		Min.	Standard value	Max.	Unit
<b>T</b>	Code period	<b>1.20</b>	--	--	$\mu s$
<b>T0H</b>	0 code, high level time	<b>0.20</b>	<b>0.30</b>	<b>0.40</b>	$\mu s$
<b>T0L</b>	0 code, low level time	<b>0.80</b>	--	--	$\mu s$
<b>T1H</b>	1 code, high level time	<b>0.70</b>	<b>0.90</b>	<b>1.00</b>	$\mu s$
<b>T1L</b>	1 code, low level time	<b>0.20</b>	--	--	$\mu s$
<b>Trst</b>	Reset code, low level time	<b>200</b>	--	--	$\mu s$

### 3. Connection Scheme

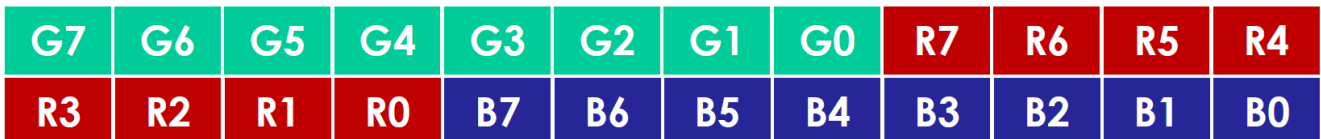


#### 4. Data Transfer Format



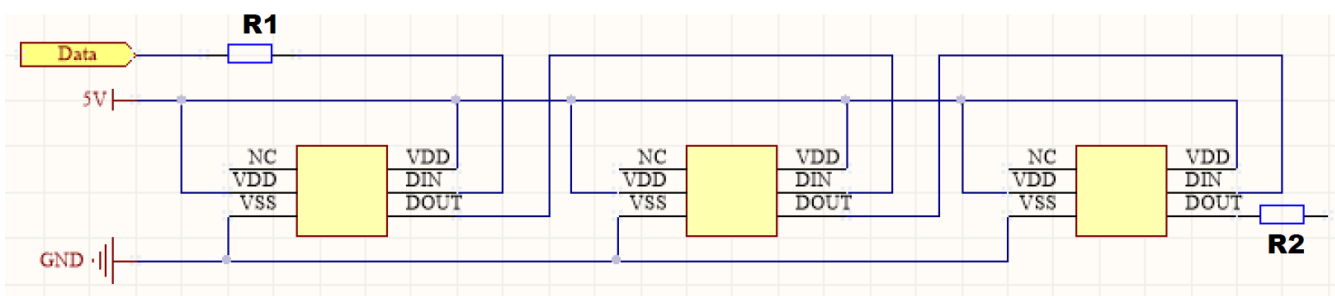
Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

#### 5. 24-bit data format



Note: high starting, in order to send data (G7 - G6 - ..... ..B0)

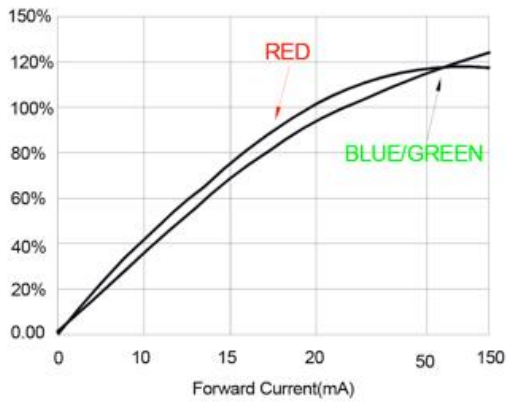
### Typical Application Circuit



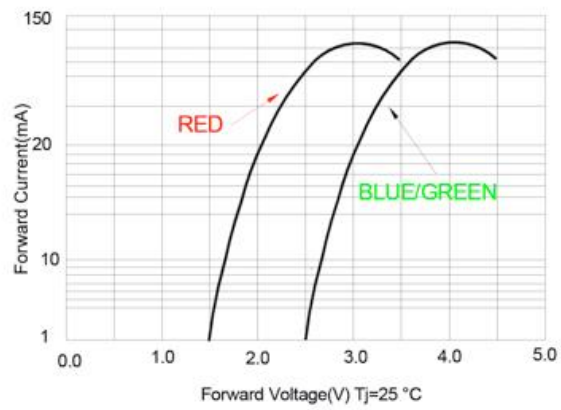
Product signal input and output must be connected in series with protection resistor R1. R1 depends on the size of the cascade amount, the greater the number of cascade, the smaller R1. The general recommended value is between 200-2KΩ, usually the recommended value is typical 500Ω.

## LED Performance Graph

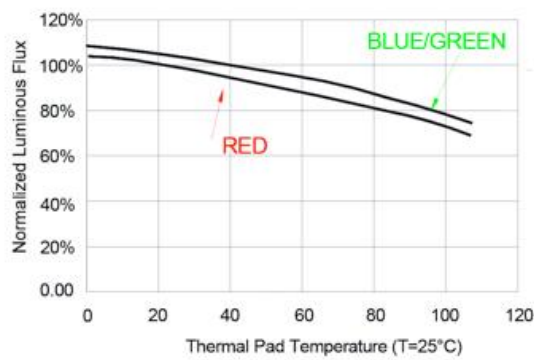
Typical Relative Luminous Flux vs. Forward Current



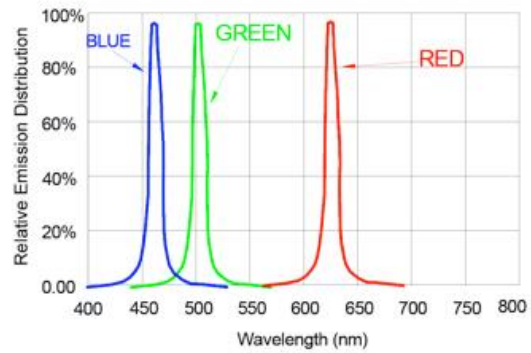
Forward Voltage vs. Forward Current



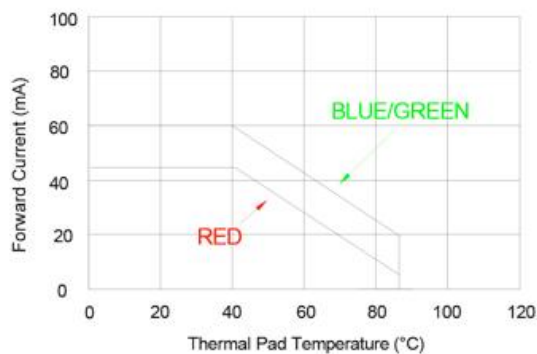
Thermal Pad Temperature vs. Relative Light Output



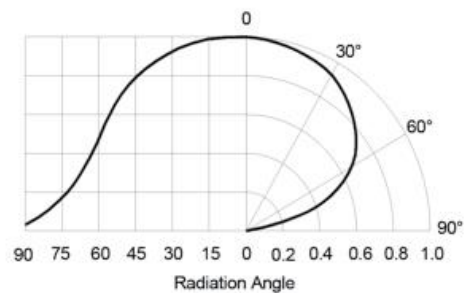
Wavelength Characteristics



Thermal Pad Temperature vs. Forward Current



Typical Radiation Pattern 120°

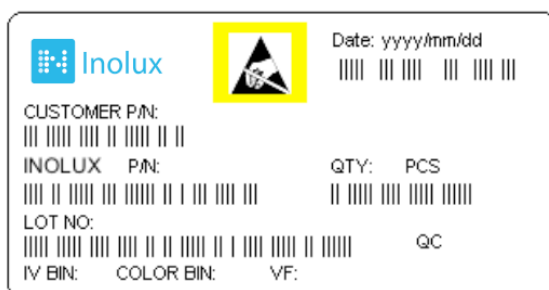




### Ordering Information

Product	Emission Color	IV(mcd)	Orderable Part Number
IN-PI55TBTPRGPB	R	400-700	IN-PI55TBTPRGPB
	G	1000-1500	
	B	200-400	

### Label Specifications



### Inolux P/N:

I	N	PI	-	55	T	B	T	(X)	R	(X)	G	(X)	B	-	X	X	X	X
		Product		Package	Die Qty.	Variation	Orientation	Current	Color	Current	Color	Current	Color		Customized Stamp-off			
Inolux		PI- Single trace IC PC- Clock Function IC		55TB = 5.0 x 5.0 x 1.6 mm (6 pins)			T = Top Mount	P=12mA	R = 624 nm	P=12mA	G = 520 nm	P=12mA	B = 470 nm					

### Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018, .....)				Month	Date	Serial

## Precautions

Please read the following notes before using the product:

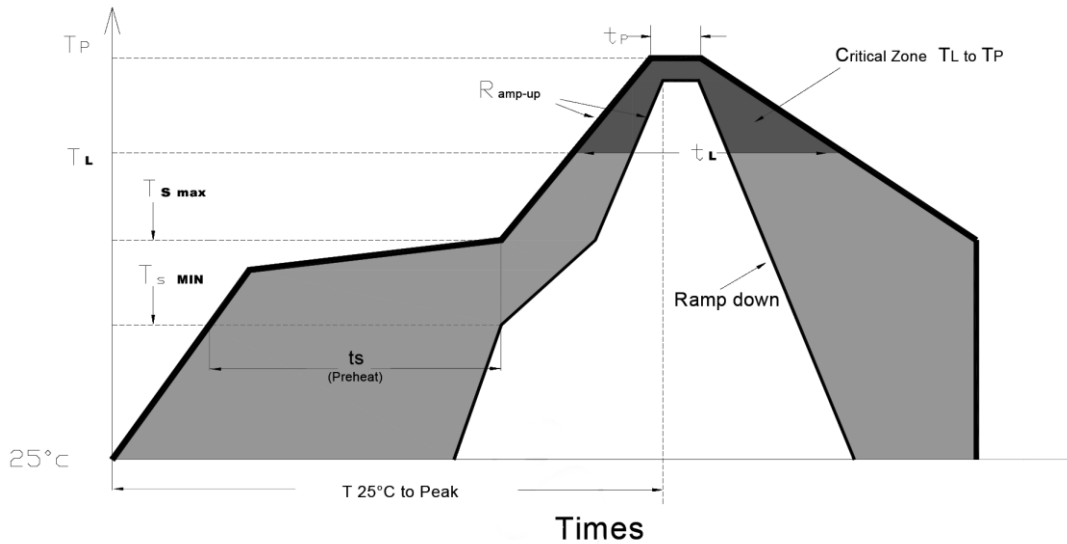
### 1. Storage

- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.
- 1.4 After opening the package, the remaining LEDs should be kept in a resealed bag.
- 1.5 The LEDs require mandatory baking before usage. Baking treatment listed below.
- 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

\*Baking treatment: 60±5°C for 24 hours.

## 2. Soldering Condition

Recommended soldering conditions:



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate (Ts <sub>max</sub> to Tp)	3°C/second max.
Preheat: Temperature Min (Ts <sub>min</sub> )	150°C
Preheat: Temperature Min (Ts <sub>max</sub> )	200°C
Preheat: Time (ts <sub>min</sub> to ts <sub>max</sub> )	60-180 seconds
Time Maintained Above: Temperature (T <sub>L</sub> )	217 °C
Time Maintained Above: Time (t <sub>L</sub> )	60-150 seconds
Peak/Classification Temperature (T <sub>P</sub> )	240 °C
Time Within 5°C of Actual Peak Temperature (tp)	<10 seconds
Ramp-Down Rate	6°C/second max.
Time 25 °C to Peak Temperature	<6 minutes max.

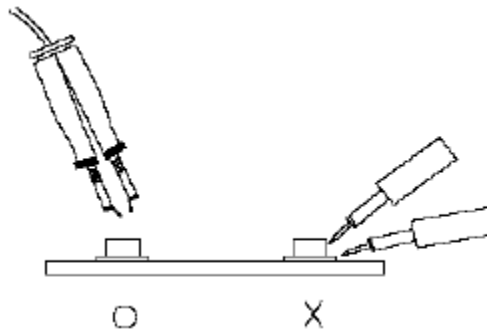
Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

### 3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



### 5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

## Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-31-2018
Format Adjustment		1.1	07-01-2018
Update intensity level		1.2	01-08-2019
Revise precautions	10	1.3	07-31-2019
Revise the drawing and spec.	1-7	1.4	02-04-2021

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